

Dual P-Channel 60-V (D-S) 175° MOSFET

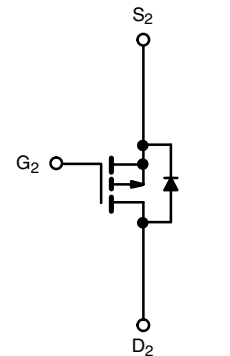
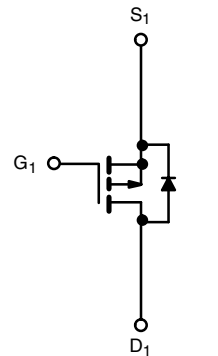
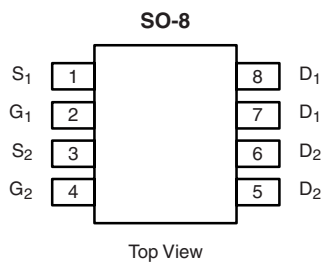
PRODUCT SUMMARY		
V_{DS} (V)	$R_{DS(on)}$ (Ω)	I_D (A)
- 60	0.120 at $V_{GS} = - 10$ V	- 3.1
	0.150 at $V_{GS} = - 4.5$ V	- 2.8

FEATURES

- Halogen-free According to IEC 61249-2-21 Definition
- TrenchFET® Power MOSFET
- Compliant to RoHS Directive 2002/95/EC



RoHS
COMPLIANT
HALOGEN
FREE
Available



Ordering Information: Si4948BEY-T1-E3 (Lead (Pb)-free)
Si4948BEY-T1-GE3 (Lead (Pb)-free and Halogen-free)

ABSOLUTE MAXIMUM RATINGS $T_A = 25$ °C, unless otherwise noted				
Parameter	Symbol	10 s	Steady State	Unit
Drain-Source Voltage	V_{DS}	- 60		V
Gate-Source Voltage	V_{GS}	± 20		
Continuous Drain Current ($T_J = 150$ °C) ^a	I_D	$T_A = 25$ °C	- 3.1	- 2.4
		$T_A = 70$ °C	- 2.6	- 2.0
Pulsed Drain Current (10 μ s Pulse Width)	I_{DM}	- 25		A
Continuous Source Current (Diode Conduction) ^a	I_S	- 2	- 1.1	
Avalanche Current	I_{AS}	15		
Single Pulse Avalanche Energy	E_{AS}	11		mJ
Maximum Power Dissipation ^a	P_D	$T_A = 25$ °C	2.4	1.4
		$T_A = 70$ °C	1.7	0.95
Operating Junction and Storage Temperature Range	T_J, T_{stg}	- 55 to 175		°C

THERMAL RESISTANCE RATINGS					
Parameter	Symbol	Typical	Maximum	Unit	
Maximum Junction-to-Ambient ^a	R_{thJA}	$t \leq 10$ s	53	62.5	°C/W
		Steady State	85	110	
Maximum Junction-to-Foot	R_{thJF}	30	37		

Notes:

a. Surface Mounted on 1" x 1" FR4 board.

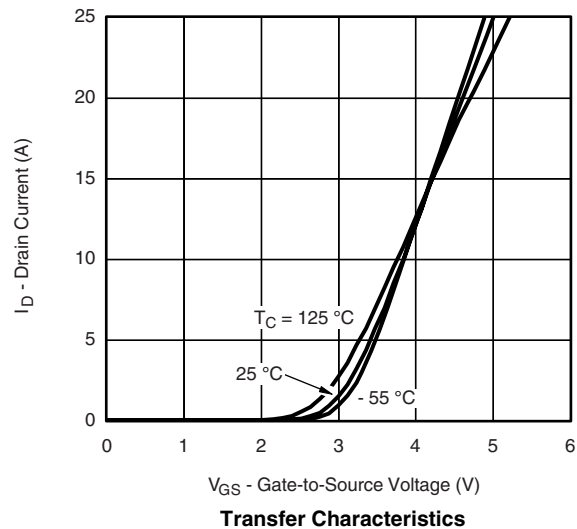
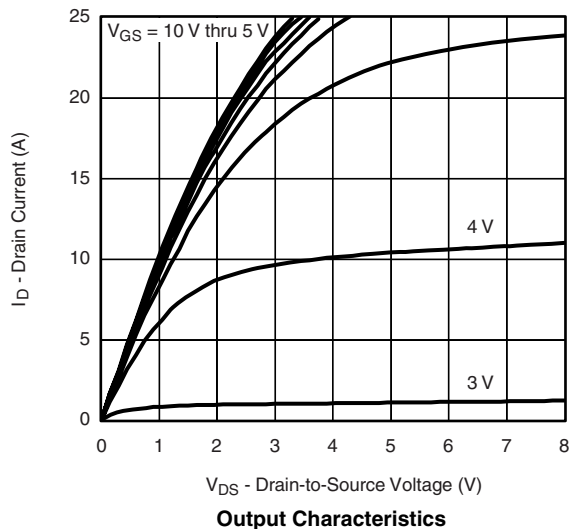
SPECIFICATIONS $T_J = 25^\circ\text{C}$, unless otherwise noted						
Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Static						
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = -250\ \mu\text{A}$	-1		-3	V
Gate-Body Leakage	I_{GSS}	$V_{DS} = 0\ \text{V}, V_{GS} = \pm 20\ \text{V}$			± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = -60\ \text{V}, V_{GS} = 0\ \text{V}$			-1	μA
		$V_{DS} = -60\ \text{V}, V_{GS} = 0\ \text{V}, T_J = 70^\circ\text{C}$			-10	
On-State Drain Current ^a	$I_{D(on)}$	$V_{DS} = -5\ \text{V}, V_{GS} = -10\ \text{V}$	-25			A
Drain-Source On-State Resistance ^a	$R_{DS(on)}$	$V_{GS} = -10\ \text{V}, I_D = -3.1\ \text{A}$		0.100	0.120	Ω
		$V_{GS} = -4.5\ \text{V}, I_D = -0.2\ \text{A}$		0.126	0.150	
Forward Transconductance ^a	g_{fs}	$V_{DS} = -15\ \text{V}, I_D = -3.1\ \text{A}$		8.5		S
Diode Forward Voltage ^a	V_{SD}	$I_S = -2\ \text{A}, V_{GS} = 0\ \text{V}$		-0.8	-1.2	V
Dynamic^b						
Total Gate Charge	Q_g	$V_{DS} = -30\ \text{V}, V_{GS} = -10\ \text{V}, I_D = -3.1\ \text{A}$		14.5	22	nC
Gate-Source Charge	Q_{gs}			2.2		
Gate-Drain Charge	Q_{gd}			3.7		
Gate Resistance	R_g	$f = 1\ \text{MHz}$		14		Ω
Turn-On Delay Time	$t_{d(on)}$	$V_{DD} = -30\ \text{V}, R_L = 30\ \Omega$ $I_D \cong -1\ \text{A}, V_{GEN} = -10\ \text{V}, R_g = 6\ \Omega$		10	15	ns
Rise Time	t_r			15	22	
Turn-Off Delay Time	$t_{d(off)}$			50	75	
Fall Time	t_f			35	55	
Source-Drain Reverse Recovery Time	t_{rr}	$I_F = -2\ \text{A}, dI/dt = 100\ \text{A}/\mu\text{s}$		30	50	

Notes:

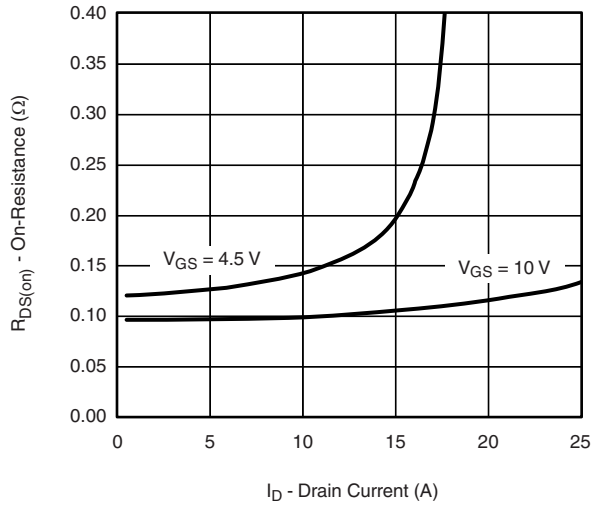
- a. Pulse test; pulse width $\leq 300\ \mu\text{s}$, duty cycle $\leq 2\%$.
- b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

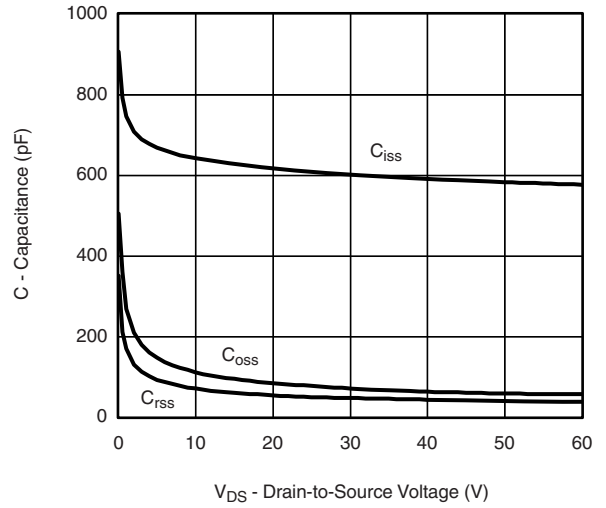
TYPICAL CHARACTERISTICS 25°C , unless otherwise noted



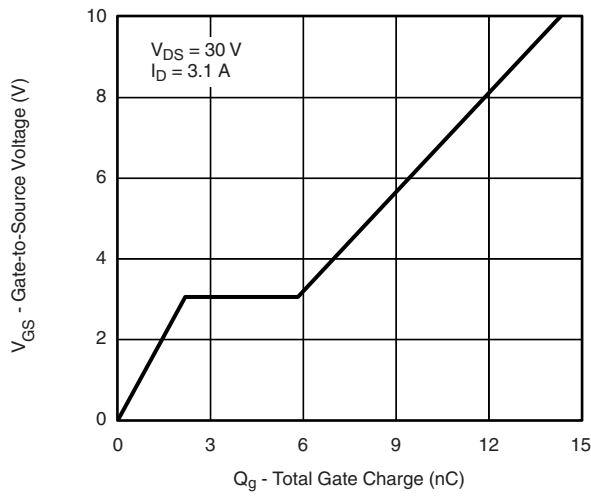
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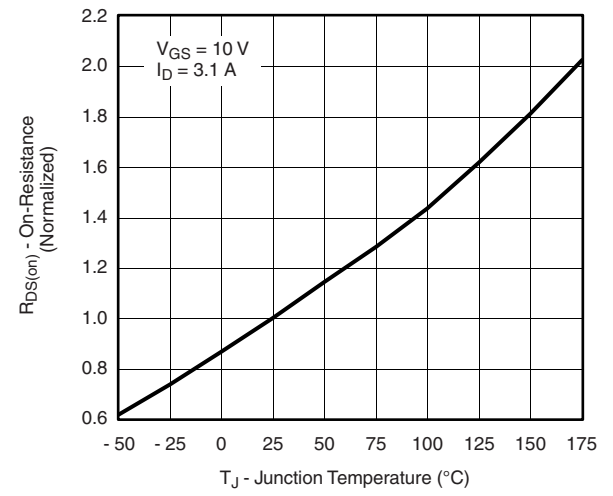
On-Resistance vs. Drain Current



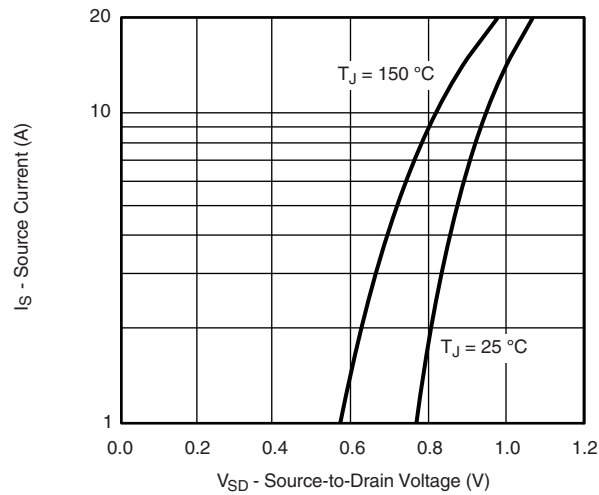
Capacitance



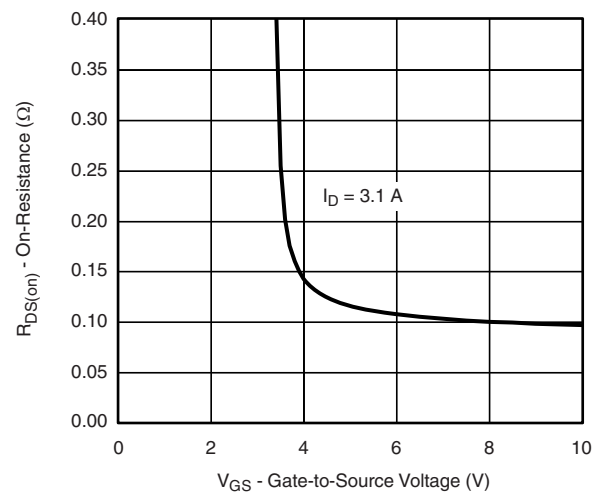
Gate Charge



On-Resistance vs. Junction Temperature

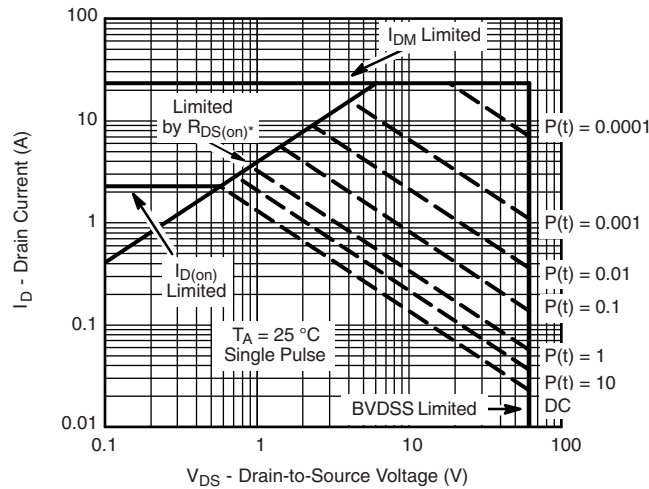
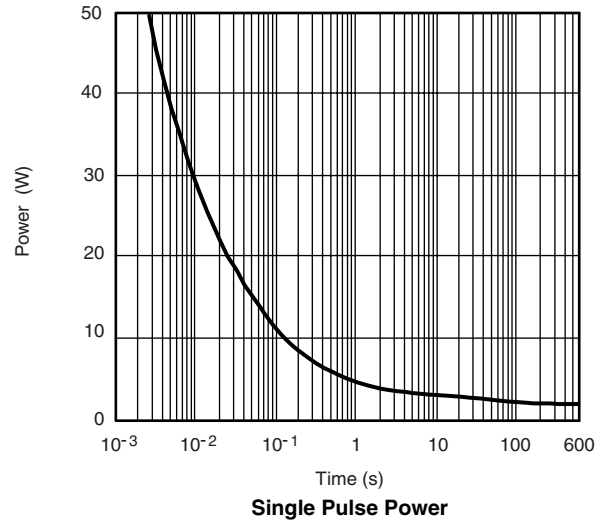
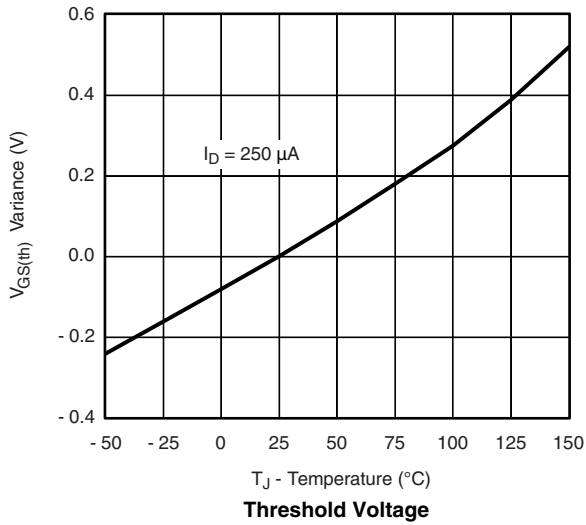


Source-Drain Diode Forward Voltage



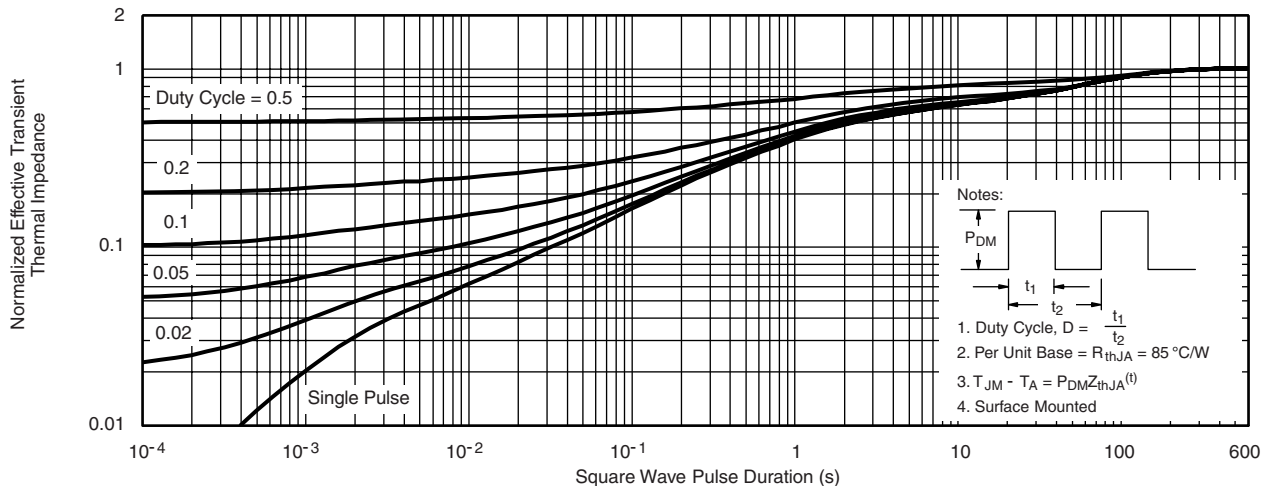
On-Resistance vs. Gate-to-Source Voltage

TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



* $V_{GS} >$ minimum V_{GS} at which $R_{DS(on)}$ is specified

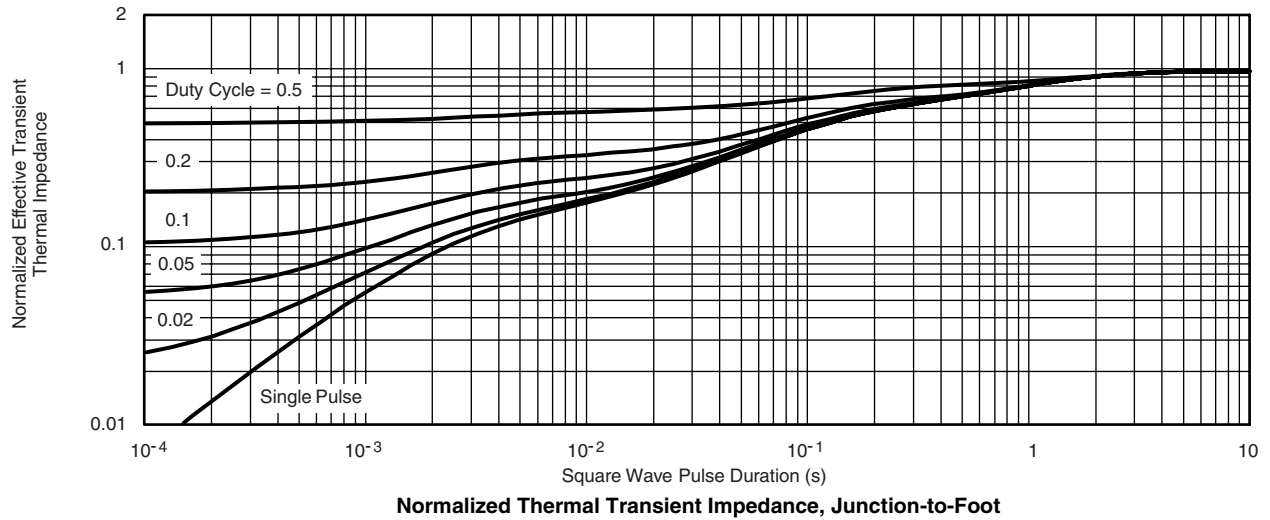
Safe Operating Area, Junction-to-Case



- Notes:
1. Duty Cycle, $D = \frac{t_1}{t_2}$
 2. Per Unit Base = $R_{thJA} = 85 \text{ }^\circ\text{C/W}$
 3. $T_{JM} - T_A = P_{DM} Z_{thJA}^{(t)}$
 4. Surface Mounted

Normalized Thermal Transient Impedance, Junction-to-Ambient

TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



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